

IEEE CAS Technical Co-Sponsorship TPC Report

Conference Name: 30th International Conference on VLSI Design
&16th International Conference on Embedded Systems, 2017,
Hyderabad, India, Jan 7-11, 2017 (**VLSID**)

Sponsorship Year: 2017

Conference Record: 40165

Conference website: www.vlsidesignconference.com

Contact Name: Nagi Naganathan

Conference Role: IEEE/ACM Liaison, Steering Committee Member

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Conference Committee

- Prof. Vishwani Agrawal – agrawavd@auburn.edu – Chair, Steering Committee
- Mr. Dasaradha Gude – General Chair, gd@invecas.com
- Prof. Vijay Raghunathan, TPC Co-Chair, vr@purdue.edu
- Dr. Kanishka Lahiri, TPC Co-Chair, kanishka.lahiri@amd.com

Description of Conference

Is the conference currently indexed in IEEE Xplore:	Yes	
Does the conference maintain a public archive of its papers:	No	
Approximate breakdown of academic/industrial attendance:	60%	40%
Approximate breakdown of local/international attendance:	70%	30%

30th International Conference on VLSI Design & 16th Internal Conference on Embedded Systems, 2017 , Jan 7-11, 2017, Hyderabad, India

•This conference is a forum for researchers and designers to present and discuss various aspects of VLSI design, EDA, embedded systems, and enabling technologies. The program will consist of regular paper sessions, special sessions, embedded tutorials, panel discussions, design contest, industrial exhibits and tutorials. *This is the premier conference/exhibition in this area in India, attracting designers, EDA professionals, and EDA tool users.* The program committee for the conference has a significant representation from the EDA research community and a large fraction of the papers published in this conference are EDA-related.

Theme: Technologies for a secure and connected world

VLSI Design Conference 2017 web site: www.vlsidesignconference.com

Sponsorship of Conference (VLSID)

Organization	Type of Sponsorship	% of total Conference
VLSI Society of India (VSI)	Financial	100%
IEEE CAS, CEDA, CS (TTTC, VLSI TC Endorsement) & Hyderabad Section	Technical	
ACM SIGDA – In Co-operation	Technical	
IEEE Conference Publications (CPS)	Publications	

TPC Review Process

- TPC Members – 111 (world wide)
- Total Number of reviewers – 259 (world wide)
- Reviewers for each paper – 3 (Minimum)
- TPC Meeting held in Bangalore, India for members in India
- TPC Meeting held at Princeton University for members based in the US

Statistics of Paper Submissions

- Total Submissions – 292
- Number of Papers Accepted – 71
- Acceptance Rate – 24 %

Technical Program

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- Total Attendees – 1860

Invited Speakers

- V.K.Saraswat, Former Secy of Defence and R&D, Former chief DRDO, Member, NITI Ayog
- Sanjay Jha, CEO, Global Foundries
- Walden C. Rhines, CEO, Mentor Graphics
- Venkat Matella, CEO, Redpine Signals
- Jaswinder Ahuja, SVP, Cadence and MD, Cadence India
- Jennifer Wong, VP, Xilinx
- Rajesh Banginwar, Principal Engineer, Intel
- Pulipati Madhav, Photonics Valley Corp

Conference Program highlights - Sponsors

- Sponsors
 - Silicon Sponsor
 - Global Foundries
 - INVECAS
 - Platinum Sponsor
 - Qualcomm
 - Xilinx
 - Gold Sponsor
 - AMD
 - Cadence
 - Intel
 - Mentor Graphics
 - Bronze Sponsor
 - Synopsys

Conference Program highlights- Exhibitors

- GLOBALFOUNDRIES Engineering Private Limited
- INVECAS
- XILINX India Technology Services Private Limited
- Qualcomm India Private Limited
- Cadence Design Systems India Private Limited
- Mentor Graphics India Private Limited
- AMD Research & Development India Private Limited
- Intel India
- Synopsys India EDA software Private Limited
- VEDA IIT
- Firstpass Semiconductors Private Limited
- Institute Of Silicon Systems Private Limited
- The Dini Group
- Redpine Signals Inc.
- Cognitive Design Technologies Private Limited
- Keysight Technologies Private Limited
- Dorado Design Automation Inc.
- Microsemi India Private Limited
- Album Semiconductors Private Limited